										RE\	/ISK	ONS													
LTR						D	ESCI	RIPTI	ION								Ţ	DATE	(YR-I	MO-D			PRO		
В	Add ca to cas Change	se ou	utline	es E	. F.	and	vice 2.	ty Ed	pe (	01. rial	Add cha	l vei inge:	ndor s th	· CA	GE gho	1832 ut.	4	88	DEC	. 08	3	4/.4	/. <sub>}</sub>	k	
	•																								
				•																					
	JRRE	NT	CA	GE	E C	OE	ÞΕ	67	26	8	1					· ·									
REV		+		1	<u> </u>	_		_	_	┝		-	-			┝	-	_	Н	_	┝				H
REV	<u>'</u>	+	-	╁	-	l-	-	┝	-	-	├─	$\vdash$	Н				┝	-		_		Н			Н
SHEET	-	┿	+	╁╌	-	-	<del> </del>	┝			╁						<u> </u>	┢		Т					П
<del></del>		1	L_ REV	<u> </u>	В	В		В	В	В	T		В	В	В		一								
	HEETS		HEET		1	2	3	Η_	5	6	7	8	9	10	11										
PMIC	N/A				PREPARED BY M. // DEFENSE EL						CTRO				CEN	ITER									
	STANDARDIZED  MILITARY  DRAWING  APPROVED BY  APPROVED BY				M	ICRO -INF	OCIR PUT,	MUL	r, D	IGI7 LEXE	AL,	HI(	SH-S	PEED IC S	CM( ILI(	OS,	QUAD								
FOR US	DRAWING SE BY ALL ND AGENC PARTMENT	DEPA	RTMEN	VTS	<b> </b>	WING 30 VISIO			AL D	158	6		1	SIZE A		_1	49	33	}			62	-86	382	23
AM	SC N/A				l ''-					В			1	S	HEE	T	. •	l	(	OF	11				

DESC FORM 193-1 SEP 87 \* U.S. GOVERNMENT PRINTING OFFICE: 1987 -- 748-129/60912

5962-E993-3

1. SCOPE									
1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1. $\overline{2.1}$ of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".									
1.2 Part number. The complete part num	er shall be as shown in the following example:								
5962-86823 <u>01</u>	<u> </u>								
Drawing number Device (1.2.	ype Case outline Lead finish per ) (1.2.2) MIL-M-38510								
1.2.1 Device type. The device type shall identify the circuit function as follows:									
Device type Generic num	er Circuit function								
01 54HC158	Multiplexer, quad 2-input (inverted out	out)							
1.2.2 <u>Case outlines</u> . The case outlines as follows:	shall be as designated in appendix C of MIL-M-38510,	and							
Outline letter	Case outline								
E D-2 (16-lead, .840" x .310" x .200"), dual-in-line package F F-5 (16-lead, .440" x .285" x .085"), flat package 2 C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package									
1.3 Absolute maximum ratings. $1/$									
Supply voltage range DC input voltage DC output voltage DC output voltage DC output current DC V <sub>CC</sub> or GND current Storage temperature range Maximum power dissipation (PD) 2/ - Lead temperature (soldering, 10 Seco Thermal resistance, junction-to-case Cases E, F, and 2 Junction temperature (TJ)									
1/ Unless otherwise specified, all voltages are referenced to ground. $\overline{2}$ / For $T_C = +100^{\circ}C$ to $+125^{\circ}C$ , derate linearly at 12 mW/ $^{\circ}C$ .									
STANDARDIZED MILITARY DRAWING	SIZE 5962-86823								

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444

SHEET

REVISION LEVEL

1.4 Recommended	operating	conditions.
-----------------	-----------	-------------

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification and standard</u>. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

**MILITARY** 

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
  - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

## STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444 SIZE A 5962-86823 REVISION LEVEL SHEET 3

TABLE I. <u>Electrical performance characteristics</u> .												
Test	Symbol		s <u>1/</u>	Group A	Lim	its	Unit					
		-55 C < 1C <	+125 C	subgroups	Min	Max						
High level output voltage	V <sub>OH</sub>	   YIN = VIH or VIL     IO  < 20 µA	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	1, 2, 3	1.9 4.4 5.9		٧					
		I <sub>0</sub>   < 4.0 mA	V <sub>CC</sub> = 4.5 V		3.7							
	   	     I <sub>O</sub>   <u>&lt;</u> 5.2 mA	V <sub>CC</sub> = 6.0 V		5.2							
Low level output voltage	v <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>     I <sub>O</sub>   < 20 μA	VCC = 2.0 V VCC = 4.5 V VCC = 6.0 V	1, 2, 3		0.1 0.1 0.1	٧					
		I <sub>0</sub>   <u>&lt;</u> 4.0 mA	V <sub>CC</sub> = 4.5 V			0.4						
	1	     I <sub>O</sub>   <u>&lt;</u> 5.2 mA 	V <sub>CC</sub> = 6.0 V	   		0.4						
High level input voltage	V <sub>IH</sub>	2/	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	1,2,3	1.5 3.15 4.2		V					
Low level input voltage	V <sub>IL</sub>	2/	2/			0.3	V     					
Input capacitance	CIN	V <sub>IN</sub> = 0 V; T <sub>C</sub> = +2   see 4.3.1c	4		10	   pF 						
Quiescent current	I <sub>C</sub> C	V <sub>CC</sub> = 6.0 V; V <sub>IN</sub> =	1,2,3		160	   μ <b>A</b>						
Input leakage current	IIN	V <sub>CC</sub> = 6.0 V; V <sub>IN</sub> =	1,2,3		<b>±</b> 1	μА						
Functional tests		See 4.3.1d		7	] 	<u> </u>	!   					

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING	SIZE <b>A</b>		5962-8	36823	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	В	SHEET	4

	T		1/	16	Lin	its	Unit	
Test	Symbol   	Conditions   -55°C <u>&lt;</u> T <sub>C</sub> <u>&lt;</u> 1	125°C 1/	Group A    subgroups  	Min	Max	1	
Propagation delay, data to output Y	tpHL tpLH	T <sub>C</sub> = +25°C, C <sub>L</sub> = 50 pF ±10% See figure 4	VCC = 2.0 V VCC = 4.5 V VCC = 6.0 V	9		140 28 24	ns	
	-     	T <sub>C</sub> = -55°C, +125°C   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	10,11		210 42 36	ns	
Propagation delay, select to output Y	tpHL tpLH	T <sub>C</sub> = +25°C,   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	   9   		160   32   27	ns	
	.     	T <sub>C</sub> = -55°C, +125°C   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	10,11	 	240   48   41	ns 	
Propagation delay, output enable to output Y	t <sub>PHL</sub>	T <sub>C</sub> = +25°C,   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	9	 	   160   32   27	l ns	
		   T <sub>C</sub> = -55°C, +125°C   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V   V <sub>CC</sub> = 4.5 V   V <sub>CC</sub> = 6.0 V	10,11	 	   240   48   41	   ns   	
Transition time	tTLH tTHL	T <sub>C</sub> = +25°C,   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V   V <sub>CC</sub> = 4.5 V   V <sub>CC</sub> = 6.0 V	9		75   15   13	   ns   	
	† 	T <sub>C</sub> = -55°C, +125°C   C <sub>L</sub> = 50 pF ±10%   See figure 4	V <sub>CC</sub> = 2.0 V   V <sub>CC</sub> = 4.5 V   V <sub>CC</sub> = 6.0 V	1		110 22 19		

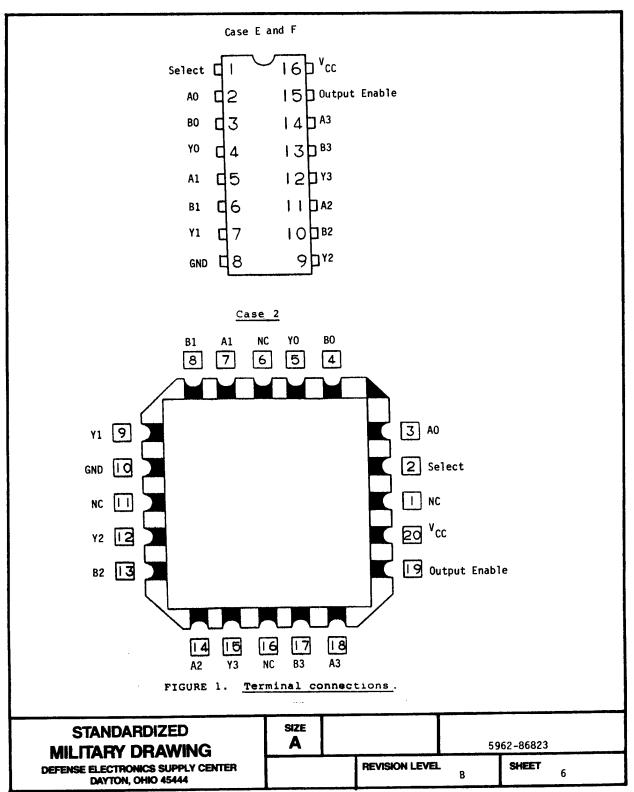
For a power supply of 5 V ±10 percent the worst case output voltage (V<sub>OH</sub> and V<sub>OL</sub>) occur for H<sub>C</sub> at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5 V and 4.5 V respectively. (The V<sub>IH</sub> value at 5.5 V is 3.85 V). The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>OZ</sub>) occur for CMOS at the higher voltage and so the 6.0 V values should be used Power dissipation capacitance (CPD), typically 40 pF, determines the no load dynamic power consumption, P<sub>D</sub> = CPD V<sub>CC2</sub> f + I<sub>CC</sub> V<sub>CC</sub>, and the no load dynamic current consumption, IS = CPD V<sub>CC</sub> f + I<sub>CC</sub>.

 $\underline{2}/$  Test not required if applied as a forcing function for  $v_{OH}$  or  $v_{OL}$ .

3/ AC testing at  $V_{CC} = 2.0 \text{ V}$  and  $V_{CC} = 6.0 \text{ V}$  shall be guaranteed, if not tested, to the specified parameters.

 $\underline{4}/$  Transition time (t<sub>TLH</sub>, t<sub>THL</sub>), if not tested, shall be guaranteed to the specified parameters.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-	-86823
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LE	<b>EVEL</b> B	SHEET 5



DESC FORM 193A SEP 87

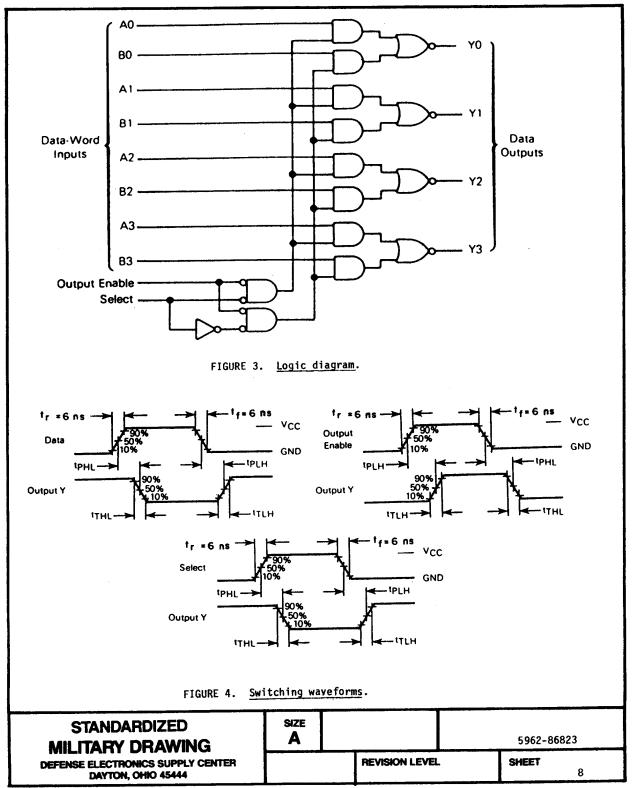
☆U.S. GOVERNMENT PRINTING OFFICE: 1987 - 748-129-66913

Output	Output		nputs	Outputs
enable	Select	Α	В	Y
Н	Х	Х	X	н
L	L	L	Х	н
L	L	н	Х	L
L	н	х	L	н
L	н	х	н	L

FIGURE 2. Truth table.

STANDARDIZED MILITARY DRAWING	SIZE A		59	62-86823		
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL		SHEET	7	

DESC FORM 193A SEP 87



- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method  $\overline{5005}$  of MIL-SID-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 4 ( $C_{
      m IN}$  measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance. Test all applicable pins on 5 devices with no failures.
    - d. Subgroup 7 tests sufficient to verify truth table.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.

STANDARDIZED MILITARY DRAWING	SIZE A		5962	2-86823	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVE	L	SHEET 9	

DESC FORM 193A

± U. S. GOVERNMENT PRINTING OFFICE: 1988-550-547

- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
  - (2)  $T_A = +125$ °C, minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

Electrical test requirements. TABLE II.

MIL-STD-883 test requirements	Subgroups (per method   5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,9
Group A test requirements (method 5005)	1,2,3,7,9, 10**,11**
Groups C and D end-point electrical parameters (method 5005)	1,2,3

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
  - 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
  - 6.2 Replaceability. Replaceability is determined as follows:
    - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
    - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/66204--.

STANDARDIZED MILITARY DRAWING	SIZE A		2-86823	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		 REVISION LEVEL	В	SHEET 10

<sup>\*</sup>PDA applies to subgroup 1.
\*\*Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.
- 6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing   part number	Vendor   CAGE   number	Vendor   similar part   number <u>1</u> /	Replacement  military specification   part number		
5962-8682301EX	01295   04713   18324   18714   27014	SNJ54HC158J   54HC158/BEAJC   54HC158A/BEA   CD54HC158F/3A   MM54HC158J/883	M38510/66204BEX		
5962-8682301FX	18324	54HC158A/BFA	M38510/66204BFX		
5962-86823012X	01295 04713 18324 27014	SN54HC158FK   54HC158M/B2AJC   54HC158A/B2A   MM54HC158E/883	M38510/66204B2X		

Vendor CAGE number	Vendor name and address			
01295	Texas Instruments, Inc P.O. Box 6448 Midland, Tx 79701			
04713	Motorola, Inc. 7402 South Price Road Tempe, AZ 85283			
18324	Signetics Corporation 4130 South Market Court Sacramento, CA 95834			
18714	GE/RCA Corporation Solid State Division Route 202 Somerville, NJ 08876			
27014	National Semiconductor Corp. 2900 Semiconductor Dr. Santa Clara CA 95051			

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962		2-86823	
			REVISION LEVEL	В	SHEET 11